



DRILL TOLERANCE  
FOR 8MIL DRILL +0/-8MIL



COMPONENTS MARKED 'DNP' SHOULD NOT BE MANUFACTURED. COMPONENTS MARKED 'DNP' SHOULD NOT BE MANUFACTURED.  
ASSEMBLY VARIANT: [No Variations] ASSEMBLY VARIANT: [No Variations]

LAYER	TRACE WIDTH	SPACING	IMPEDANCE	REFERENCE LAYER
TOP	10 MIL	8 MIL	90 OHM +/-10%	L2_GND-PLANE
TOP	7 MIL	16 MIL	100 OHM +/-10%	L2_GND-PLANE
BOTTOM	7 MIL	16 MIL	100 OHM +/-10%	L3_PWR-PLANE

The Stackup Legend below this is static. If you change the stackup, update the Legend.

Layer Name	Order	Copper Thickness	Dielectric Material
Top Solder Mask	(.GTS)		Solder Resist
TOP LAYER	(.GTL)	1.4mil	FR-4
L2_PWR-PLANE	(.G01)	1.4mil	FR-4
L2_GND-PLANE	(.G02)	1.4mil	FR-4
L3_PWR-PLANE	(.G03)	1.4mil	FR-4
BOTTOM LAYER	(.GBL)	1.4mil	FR-4
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)  
2000MIL X 3000MIL

Number of Layers : 4  
MIN. TRACK WIDTH: 4 MIL  
MIN. CLEARANCE: 4 MIL  
MIN. VIA PAD SIZE: 18 MIL

MINIMUM ANNULAR RING 0.127mm (5ML) EXTERNAL  
PER IPC-D-275 CLASS 2 LEVEL C

REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:

FR-408  FR-4 High Tg  OTHER

THICKNESS:  63 MIL (1.6mm) +/-10%  OTHER

TOLERANCE:  ANSI IPC-6012 TYPE 3 CLASS 2

OTHER +/-

BOW & TWIST:  ANSI IPC-6012 TYPE 3 CLASS 2

OTHER +/-

COPPER THICKNESS (FINISHED):

OUTER:  1.4MIL (1oz)  2MIL (1.4oz)  2.8MIL (2oz)

INNER SIGNAL:  1.4MIL (1oz)  2.8MIL (2oz)  N/A

DRILLING:

REFERENCE:  AS SHOWN  NC\_DRILL FILES

PTH MIN COPPER THICKNESS:  1MIL  OTHER

BOARD FINISH:

SILKSCREEN:  TOP  BOTTOM

SILKSCREEN COLOR:  WHITE  OTHER

SOLDER RESIST COLOR:

GREEN  BLUE  OTHER

SURFACE FINISH:

IMMERSION GOLD (ENG)  ENEPIG

IMM. TIN/SILVER OR EQUIV  OTHER

ARRAY/PANEL:

CUT AND TRIM PER MECH LAYER 1

N.C. ROUTE  V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:

ANSI IPC-A-600F CLASS ->  1  2  3

UL 94V-0  RoHS  OTHER PER ORDER

ADDITIONAL REQUIREMENTS:

MICROSECTION:  YES VIA TENTING: YES  NO

BARE BOARD ELEC. TEST:  NONE  REQUIRED  PER ORDER

MANUFACTURER'S UL:  RAIL  METAL  SILK



PROJECT TITLE:  
TIDA-00226 (ISE5001)

DESIGNED FOR:  
Public Release

FILE NAME:  
TIDA-00226 (ISE5001)

ENGINEER:

LAYOUT BY:

SCALE: 1.00

ALTIUM DESIGNER VERSION:  
10.0.0.27009

REV: 001	DATE: 06/25/2014	BY: [Redacted]	DESCRIPTION: [Redacted]	REVISIONS:	DESCRIPTION:	DATE:	BY:
1	06/25/2014	[Redacted]	INITIAL DESIGN				

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